

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Sinn-Wen CHEN

Serial No: Unassigned

Filed: September 9, 2003

For: Electromigration Effect-Insignificant Alloys And The Alloys' Designing Method

) Atty Dkt: CHEN3585/EM

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Assistant Commissioner of Patents
and Trademarks
Alexandria, Virginia 22313-1450

INFORMATION DISCLOSURE STATEMENT

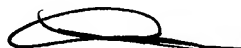
Sir:

Pursuant to Rule 37 C.F.R. §1.51(b), §1.56, §1.97, and §1.98, this Information Disclosure Statement is submitted in the above-identified patent application. A listing of documents to be published on the face of any patent granted from this application is submitted herewith on Form PTO-1449. Any other documents or information submitted for consideration by the Examiner are listed in this paper.

The Examiner is requested to acknowledge consideration of the information provided in this paper in accordance with prescribed procedures.

Please charge any additional fees or credit any overpayments in connection with this paper to Deposit Account No. 02-0200.

Respectfully submitted,



Eugene Mar
Registration No. 25,893

Date: September 9, 2003

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B/O Form PTO-1449 U.S. Department of Commerce Patent and Trademark Office Information Disclosure Statement by Applicant	Atty. Docket Number CHEN3585/EM	Serial Number Unassigned
	Applicant Sinn-Wen CHEN	
	Filing Date Concurrently Herewith - Sept. 9, 2003	Group

U.S. Patent Documents

Examiner Initial	Document Number	Date	Patentee/Applicant	Class	Subclass	Filing Date if Appropriate

Foreign Patent Documents

Examiner Initial	Document Number	Publication Date	Country/Agency	Class	Subclass	Translation	
						Yes	No

Other Documents (Including Author, Title, Date, Pertinent Pages, Place of Publication, Etc.)

	H. B. Huntington, <i>Electromigration in Metals in Diffusion In Solids: Recent Developments</i> , pp. 303-353, edited by Nowick and Burton, Academic Press, New York, 1975.
	M. Y. Hsieh et. al., <i>Electromigration of Copper in Lead</i> , J. Phys. Chem. Solids, Vol. 39, pp. 867-871, 1978
	C. K. Hu et. al., <i>Diffusion and electromigration of silver and nickel in lead-tin alloys</i> , Physical Review, Vol. 26, No. 6, pp. 2782-2789, 1982

Examiner	Date Considered
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EXAMINER: Initial if citation is considered, whether or not citation is in conformance with MPEP 609; Draw a line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.